



Product Change Notification: BLAS-27CKVC585

Date:

02-Jun-2026

Product Category:

Bluetooth Module

Notification Subject:

CCB 8293 Final Notice: Qualification of U08D as a new fabrication location of Die #2 of catalog part numbers AT24C64D-XHM-T and 24AA64T-I/ST available in 8L TSSOP (4.4mm) used in the U2 component of BM20SPKA1NBC-0001AA, BM20SPKA1NBC-Y301AA, BM20SPKS1NBC-0001AA, BM20SPKS1NBC-C001AA, BM20SPKS1NBC-C002AA, BM20SPKS1NBC-T001AA, BM20SPKS1NBC-Y003AA, BM20SPKS1NBC-Y202AB, BM20SPKS1NBC-Y202DP and BM20SPKS1NBC-Y202MA catalog part numbers (CPN) available in 40L MODULE (15x29mm) package.

Affected CPNs:

[BLAS-27CKVC585_Affected_CPN_06022026.pdf](#)

[BLAS-27CKVC585_Affected_CPN_06022026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of U08D as a new fabrication location of Die #2 of catalog part numbers AT24C64D-XHM-T and 24AA64T-I/ST available in 8L TSSOP (4.4mm) used in the U2 component of BM20SPKA1NBC-0001AA, BM20SPKA1NBC-Y301AA, BM20SPKS1NBC-0001AA, BM20SPKS1NBC-C001AA, BM20SPKS1NBC-C002AA, BM20SPKS1NBC-T001AA, BM20SPKS1NBC-Y003AA, BM20SPKS1NBC-Y202AB, BM20SPKS1NBC-Y202DP and BM20SPKS1NBC-Y202MA catalog part numbers (CPN) available in 40L MODULE (15x29mm) package.

Pre and Post Summary Changes:

*U2 Component		Pre Change			Post Change		Change (Yes/No)	
Fabrication Site	Die #1	No change in fabrication site.					No	
	Die #2	Microchip Technology Tempe – Fab 2 (TMGR)	Microchip Technology Gresham – Fab 4 (GRTM)	Microchip Technology Colorado (MCSO)	United Microelectronics Corporation (Fab 8D (U08D))		Yes	
Wafer Size	Die #1	No change in wafer size.					No	
	Die #2	8"	8"	6"	8"		Yes	

***Note:** The U2 component (AT24C64D-XHM-T and 24AA64T-I/ST) catalog part numbers has already been qualified at U08D through PCN# [NTDO-27KWWJ104](#).

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability and on-time delivery performance by qualifying a second fabrication source at United Microelectronics Corporation (Fab 8D) (U08D) site for Die #2 used in the component U2.

Change Implementation Status: In Progress

Estimated First Ship Date: 03 July 2026 (date code: 2627)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	June 2026				July 2026				
Work Week	23	24	25	26	27	28	29	30	31
Qual Report Availability	X								
Final PCN Issue Date	X								
Estimated Implementation Date					X				

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 02, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_BLAS-27CKVC585_Pre and Post Change Summary.pdf](#)

[PCN_BLAS-27CKVC585_Qualification_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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